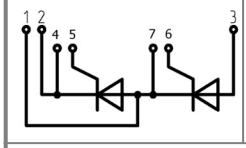
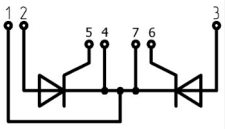
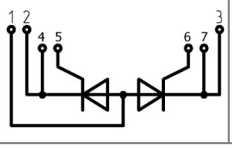
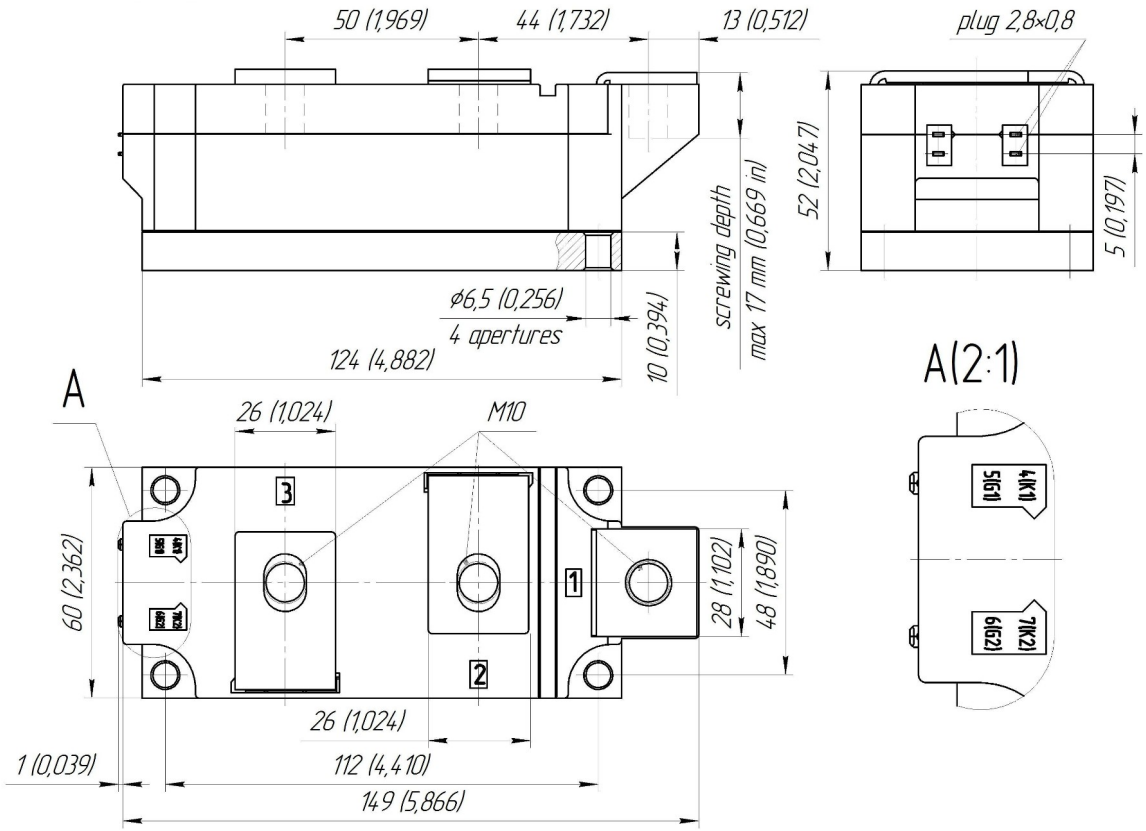
Electrically isolated base plate
Industrial standard package
Simplified mechanical design, rapid assembly
Pressure contact

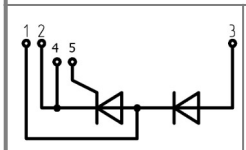
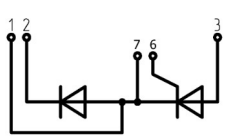
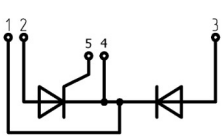
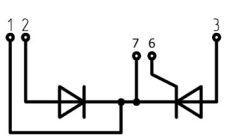
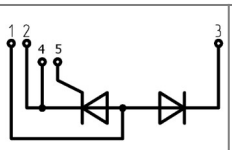
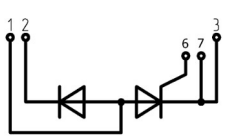
Double Thyristor Module For Phase Control MTx-240-65-A2

Mean on-state current					I_{TAV}		240 A				
Repetitive peak off-state voltage					V_{DRM}		4600...6500 V				
Repetitive peak reverse voltage					V_{RRM}						
Turn-off time					t_q		800 µs				
V_{DRM}, V_{RRM}, V	4600	4800	5000	5200	5400	5600	5800	6000	6200	6400	6500
Voltage code	46	48	50	52	54	56	58	60	62	64	65
T_j, °C	–40...+125										

MT3 **MT4** **MT5**



MT/D3 **MD/T3** **MT/D4** **MD/T4** **MT/D5** **MD/T5**

All dimensions in millimeters (inches)

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Maximum allowable mean on-state current	A	240	T_c=85 °C; 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	376		
I_{TSM}	Surge on-state current	kA	4.0 4.6	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; t_p=10 ms; single pulse; V_D=V_R=0 V; Gate pulse: I_G=2 A; t_{GP}=50 µs; di_G/dt≥1 A/µs
			4.2 4.8	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; t_p=8.3 ms; single pulse; V_D=V_R=0 V; Gate pulse: I_G=2 A; t_{GP}=50 µs; di_G/dt≥1 A/µs
I^2t	Safety factor	$A^2s\cdot10^3$	80 106	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; t_p=10 ms; single pulse; V_D=V_R=0 V; Gate pulse: I_G=2 A; t_{GP}=50 µs; di_G/dt≥1 A/µs
			73 97	T_j=$T_{j\,max}$ T_j=25 °C	180° half-sine wave; t_p=8.3 ms; single pulse; V_D=V_R=0 V; Gate pulse: I_G=2 A; t_{GP}=50 µs; di_G/dt≥1 A/µs
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	4600...6500	$T_{j\,min}$< T_j <$T_{j\,max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	4700...6600	$T_{j\,min}$< T_j <$T_{j\,max}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6\cdot V_{DRM}$ $0.6\cdot V_{RRM}$	T_j=$T_{j\,max}$; Gate open	
TRIGGERING					
I_{FGM}	Peak forward gate current	A	8	T_j=$T_{j\,max}$	
V_{RGM}	Peak reverse gate voltage	V	5		
P_G	Gate power dissipation	W	4	T_j=$T_{j\,max}$ for DC gate current	
SWITCHING					
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive (f=1 Hz)	A/µs	500	T_j=$T_{j\,max}$; V_D=$0.67\cdot V_{DRM}$; I_{TM}=2 I_{TAV}; Gate pulse: I_G=2 A; t_{GP}=50 µs; di_G/dt≥2 A/µs	
THERMAL					
T_{stg}	Storage temperature	°C	–40...+50		
T_j	Operating junction temperature	°C	–40…+125		
$T_{c\,op}$	Operating temperature	°C	–40...+125		
MECHANICAL					
a	Acceleration under vibration	m/s^2	50		

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V_{TM}	Peak on-state voltage, max	V	2.80	T_j=25 °C; I_{TM}=785 A	
$V_{T(TO)}$	On-state threshold voltage, max	V	1.10	T_j=$T_{j\,max}$;	
r_T	On-state slope resistance, max	mΩ	2.500	0.5 π I_{TAV} < I_T < 1.5 π I_{TAV}	
I_L	Latching current, max	mA	1000	T_j=25 °C; V_D=12 V; Gate pulse: I_G=2 A; t_{GP}=50 μs; di_G/dt≥1 A/μs	
I_H	Holding current, max	mA	300	T_j=25 °C; V_D=12 V; Gate open	
BLOCKING					
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	150	T_j=$T_{j\,max}$; V_D=V_{DRM}; V_R=V_{RRM}	
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage[1], min	V/μs	1000	T_j=$T_{j\,max}$; V_D=0.67·V_{DRM}; Gate open	
TRIGGERING					
V_{GT}	Gate trigger direct voltage, max	V	4.00 2.50 2.00	T_j= $T_{j\,min}$ T_j=25 °C T_j= $T_{j\,max}$	V_D=12 V; I_D=3 A; Direct gate current
I_{GT}	Gate trigger direct current, max	mA	500 300 200	T_j= $T_{j\,min}$ T_j= 25 °C T_j= $T_{j\,max}$	
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	T_j=$T_{j\,max}$; V_D=0.67·V_{DRM}; Direct gate current	
I_{GD}	Gate non-trigger direct current, min	mA	15.00		
SWITCHING					
t_{gd}	Delay time, max	μs	3.50	T_j=25 °C; V_D=1500 V; I_{TM}=I_{TAV}; di/dt=200 A/μs; Gate pulse: I_G=2 A; V_G=20 V; t_{GP}=50 μs; di_G/dt=2 A/μs	
t_q	Turn-off time[2], max	μs	800	dv_D/dt=50 V/μs; T_j=$T_{j\,max}$; I_{TM}= I_{TAV}; di_R/dt=-10 A/μs; V_R=100V; V_D=0.67 V_{DRM};	
Q_{rr}	Total recovered charge, max	μC	2600	T_j=$T_{j\,max}$; I_{TM}=1000 A; di_R/dt=-5 A/μs; V_R=100 V	
t_{rr}	Reverse recovery time, max	μs	52		
I_{rr}	Peak reverse recovery current, max	A	100		
THERMAL					
R_{thjc}	Thermal resistance, junction to case				
	per module	°C/W	0.0340	180° half-sine wave, 50 Hz	
	per arm	°C/W	0.0680		
	per module	°C/W	0.0325	DC	
	per arm	°C/W	0.0650		
R_{thch}	Thermal resistance, case to heatsink				
	per module	°C/W	0.0100		
	per arm	°C/W	0.0200		
INSULATION					
V_{ISOL}	Insulation test voltage	kV	3.00	Sine wave, 50 Hz; RMS	t=1 min
			3.60		t=1 sec
MECHANICAL					
M_1	Mounting torque (M6)[3]	Nm	6.00	Tolerance ± 15%	
M_2	Terminal connection torque (M10)[3]	Nm	12.00	Tolerance ± 15%	
m	Weight, max	g	1500		

PART NUMBERING GUIDE

MT	3	-	240	-	65	-	A2	B2	-	A2	-	N
1	2		3		4		5	6		7		8

1. Thyristor module (MT)
   Thyristor – Diode module (MT/D)
   Diode – Thyristor module (MD/T)
2. Circuit Schematic:
   3 – serial connection
   4 – common Cathode
   5 – common Anode
3. Average On-state Current, A
4. Voltage Code
5. Critical rate of rise of off-state voltage
6. Group of turn-off time (dv_D/dt=50 V/μs)
7. Package Type (M.A2)
8. Ambient Conditions:
   N – Normal

NOTES

[1] Critical rate of rise of off-state voltage

Symbol of group	A2
$(dv_D/dt)_{crit}$, V/μs	1000

[2] Turn-off time (dv_D/dt=50 V/μs)

Symbol of group	B2
t_q, μs	800

[3] The screws must be lubricated

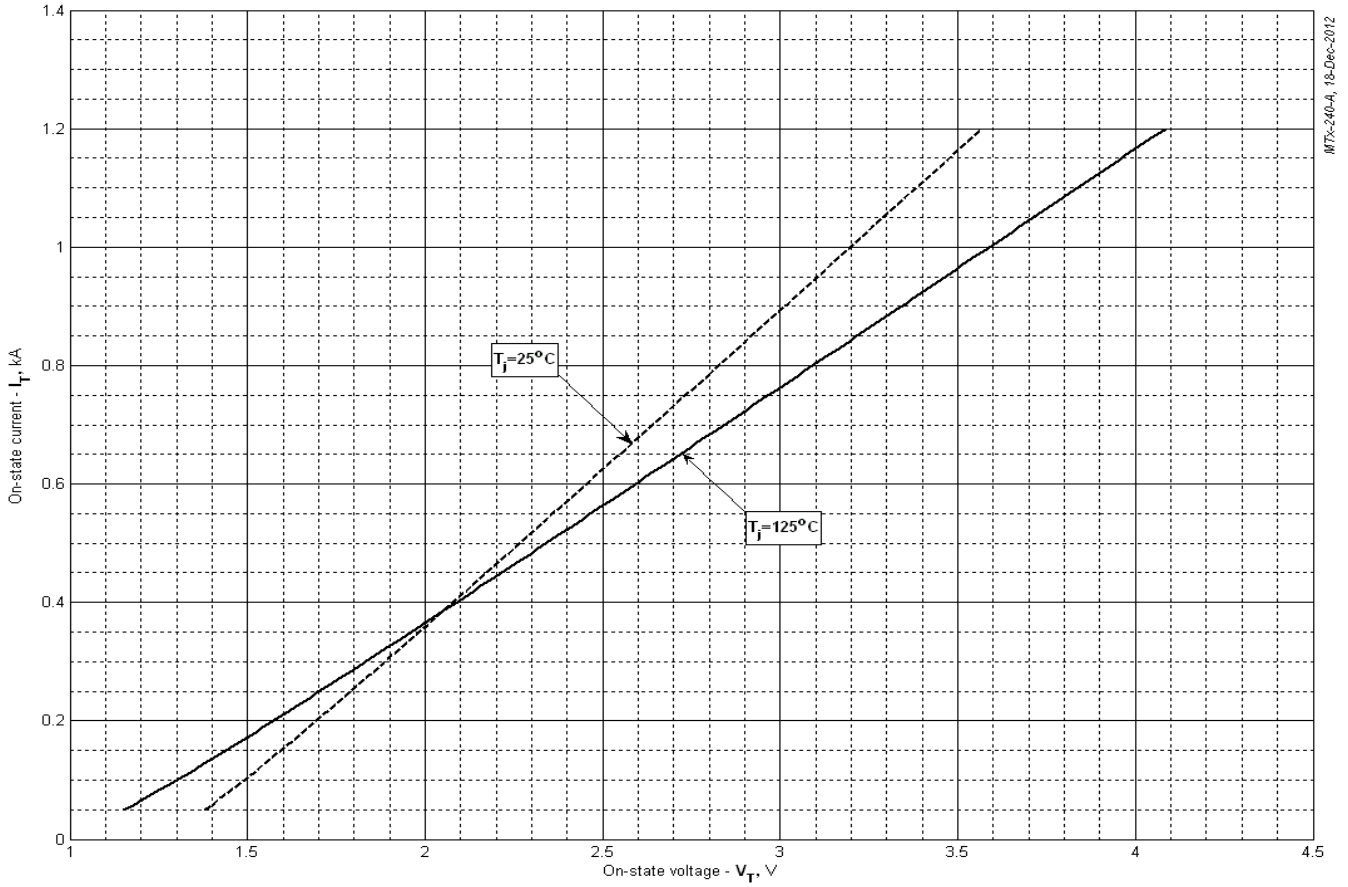


Fig 1 – On-state characteristics of Limit device

Analytical function for On-state characteristic:

$$V_T = A + B \cdot i_T + C \cdot \ln(i_T + 1) + D \cdot \sqrt{i_T}$$

	Coefficients for max curves	
	T_j = 25°C	$T_j = T_{j\,max}$
A	1.227736	0.949110
B	1.808776	2.425010
C	-0.246855	-0.329693
D	0.331594	0.442867

On-state characteristic model (see Fig. 1)

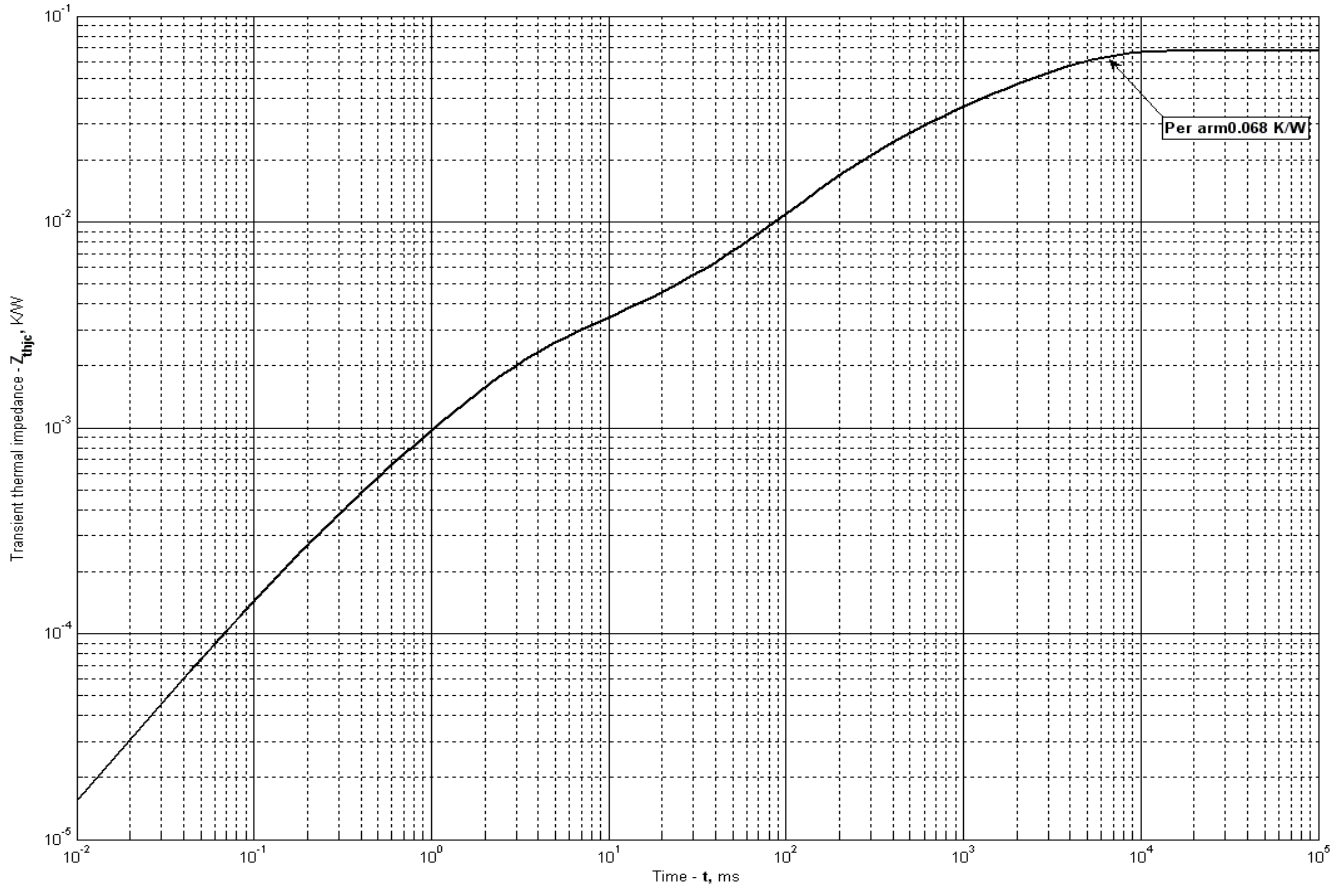


Fig 2 – Transient thermal impedance

Analytical function for Transient thermal impedance junction to case Z_{thjc} for DC:

$$Z_{thjc} = \sum_{i=1}^{n} R_i \left(1 - e^{-\frac{t}{\tau_i}} \right)$$

Where ***i*** = 1 to ***n***, ***n*** is the number of terms in the series.

t = Duration of heating pulse in seconds.

Z_{thjc} = Thermal resistance at time t.

R_i = Amplitude of p_{th} term.

t_i = Time constatnt of r_{th} term.

i	1	2	3	4	5	6
R_i, K/W	0.0385	0.01253	0.0144	0.0007273	0.001871	0.0001367
τ_i, s	3.124	0.8558	0.1999	0.009185	0.002295	0.000238

Transient thermal impedance junction to case Z_{thjc} model (see Fig. 2)

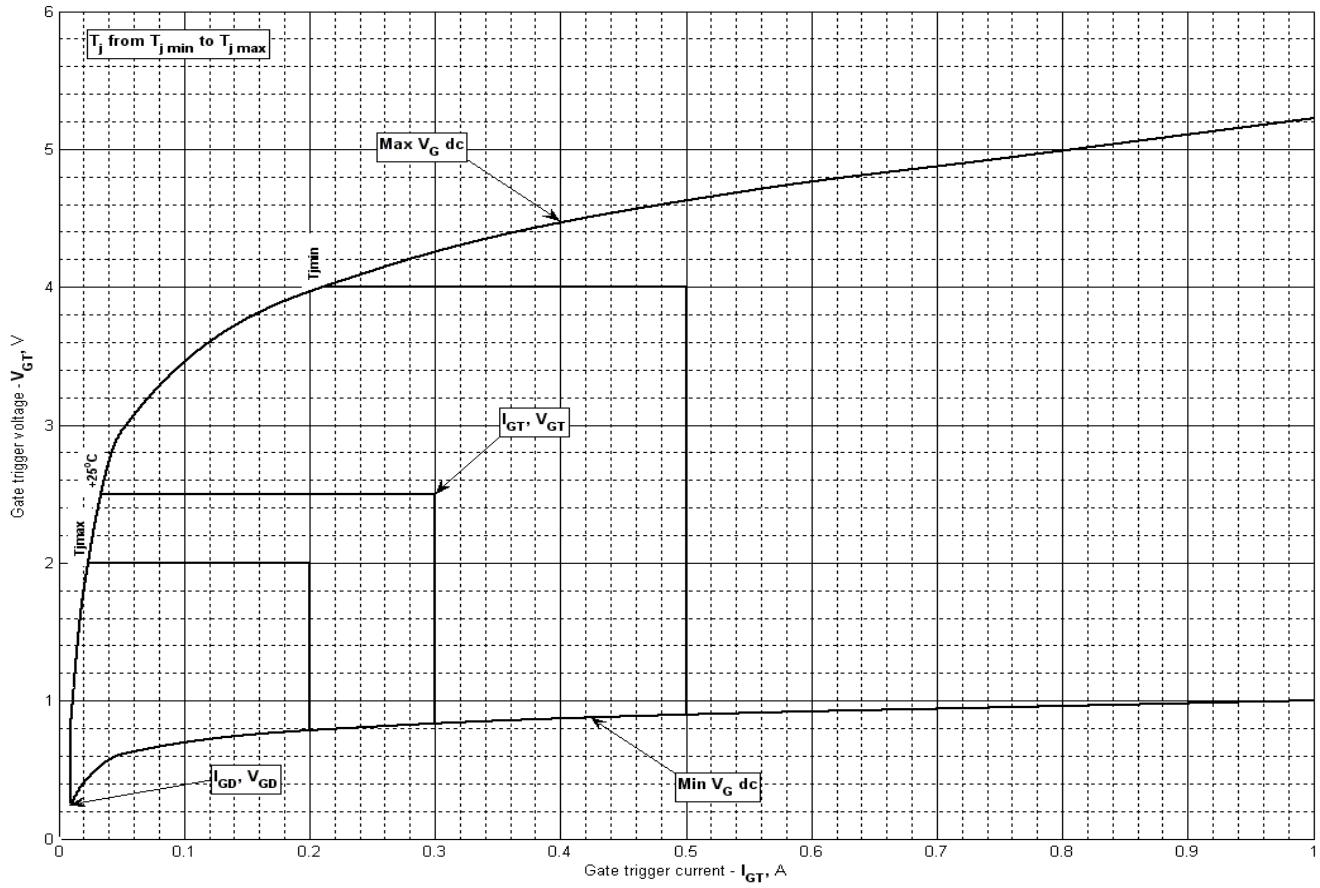


Fig 3 – Gate characteristics – Trigger limits

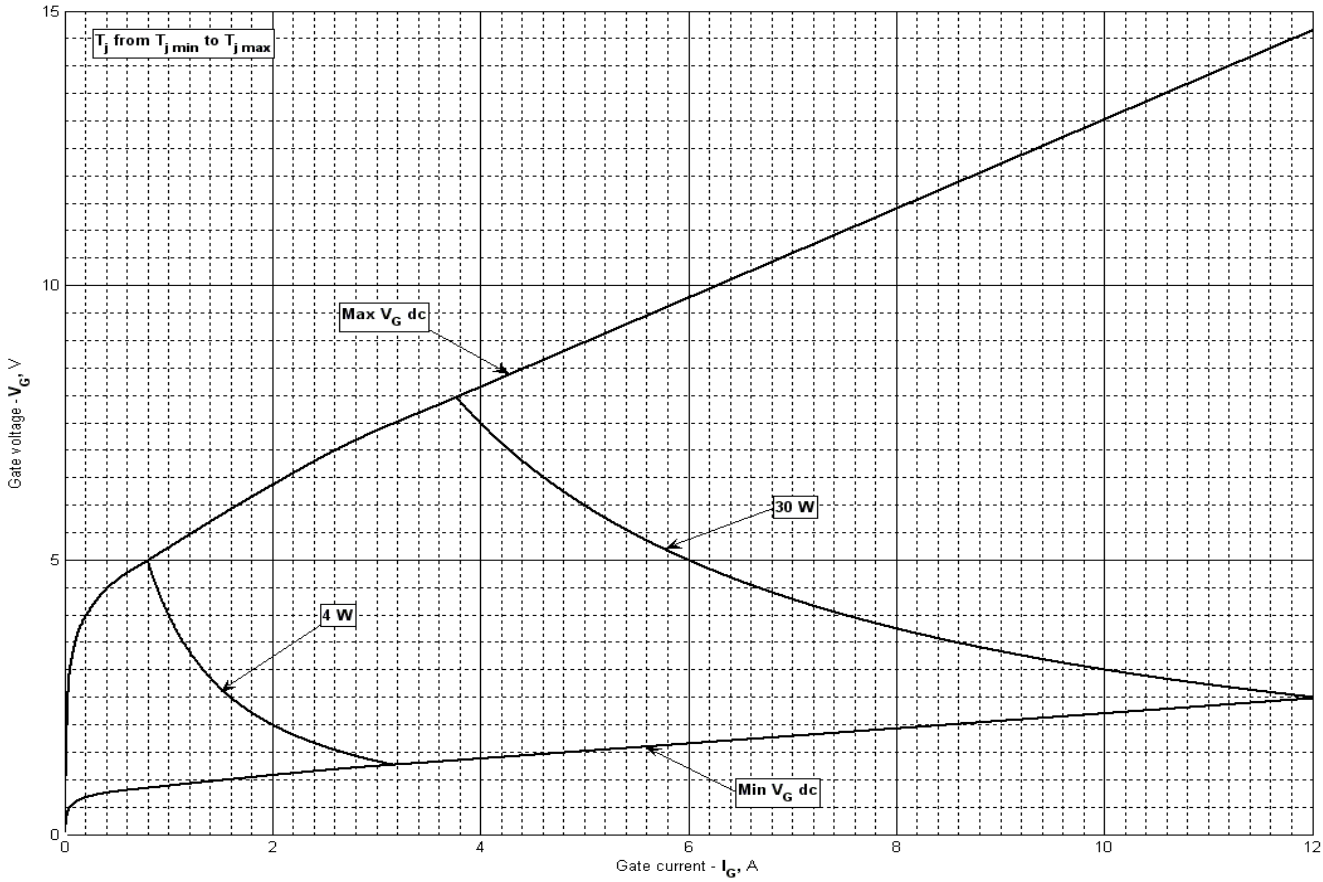


Fig 4 - Gate characteristics – Power curves

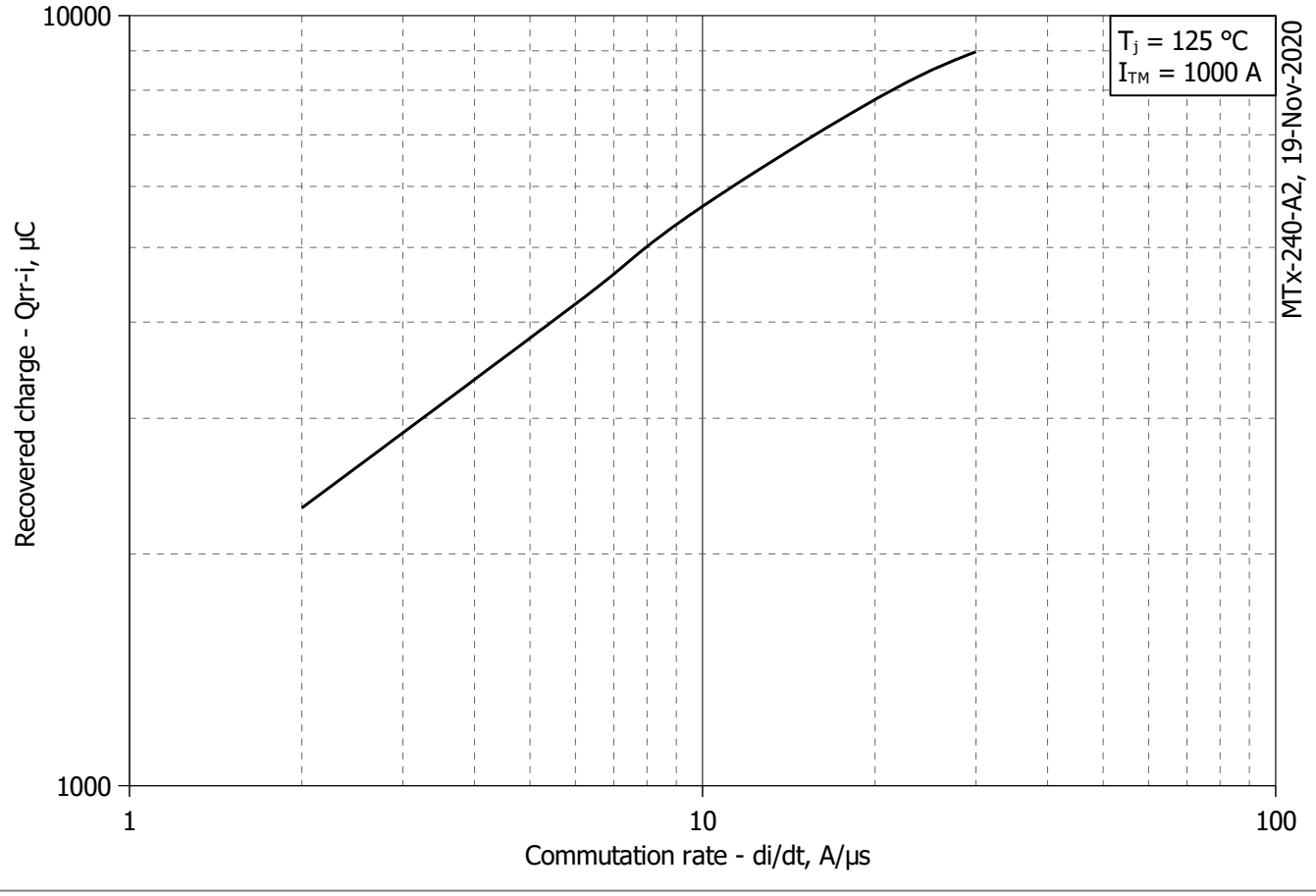


Fig 5 - Total recovered charge, Q_{rr-i} (integral)

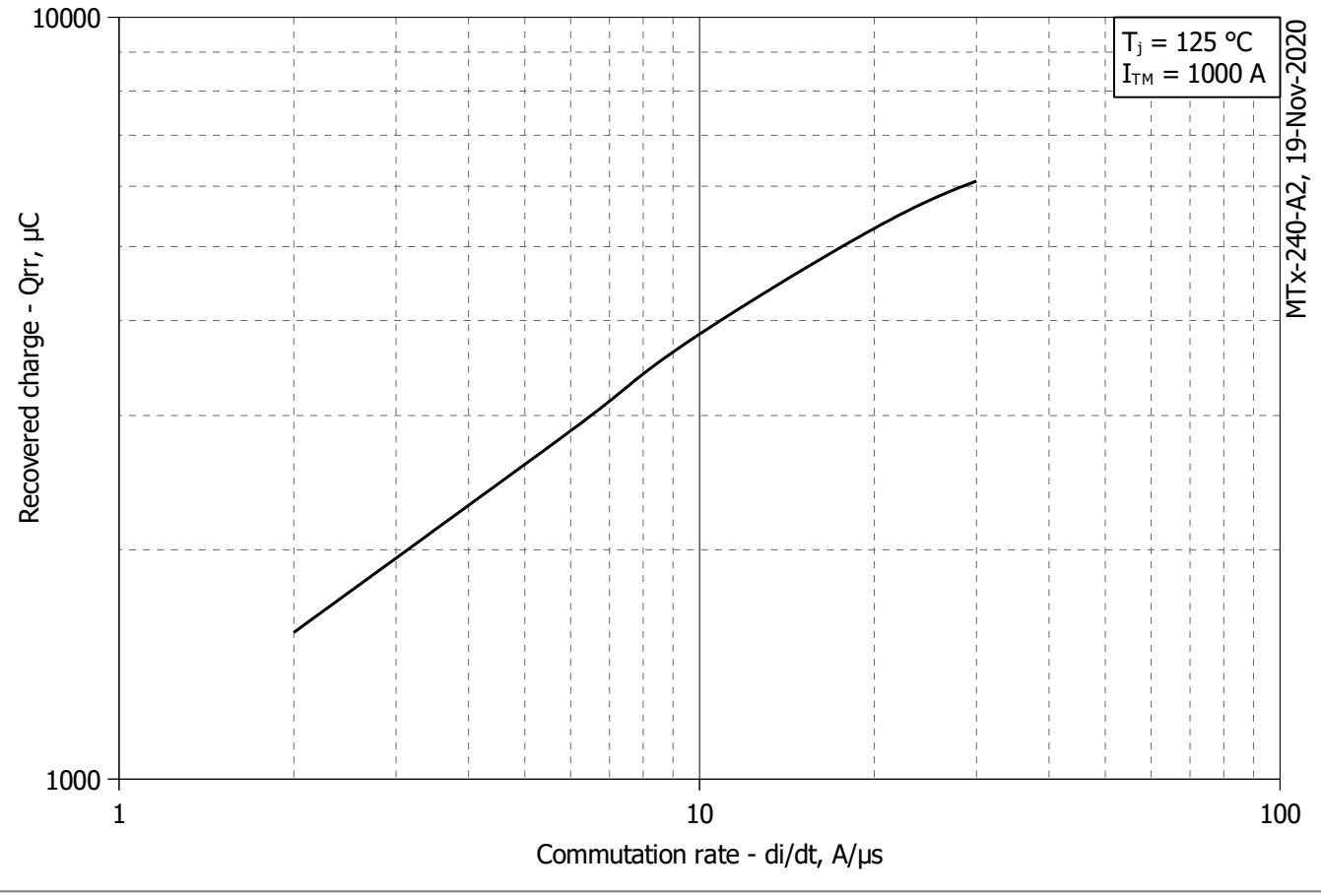


Fig 6 - Recovered charge, Q_{rr} (25% chord)

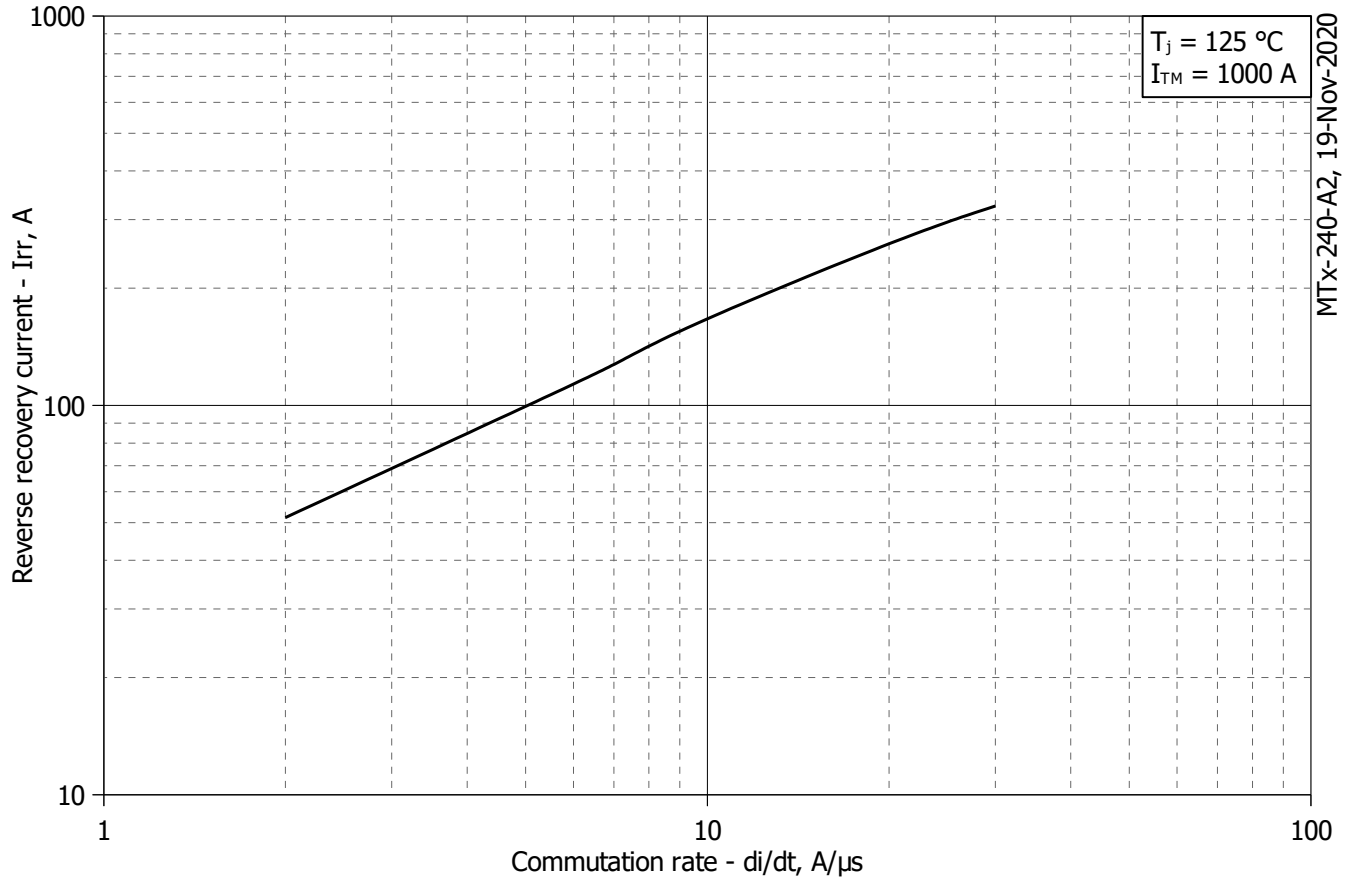


Fig 7 - Maximum reverse recovery current, I_{rr}

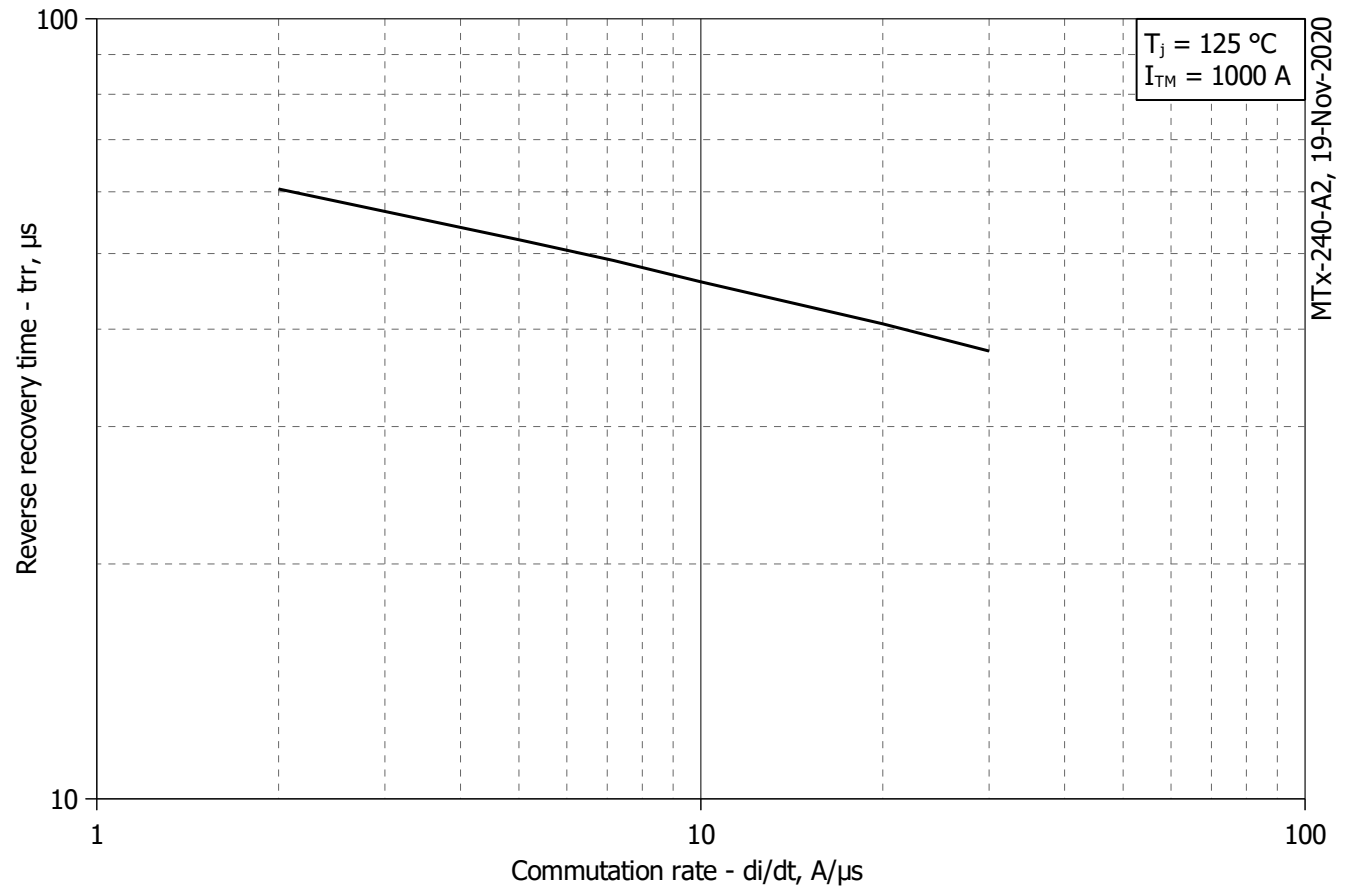


Fig 8 - Maximum recovery time, t_{rr} (25% chord)

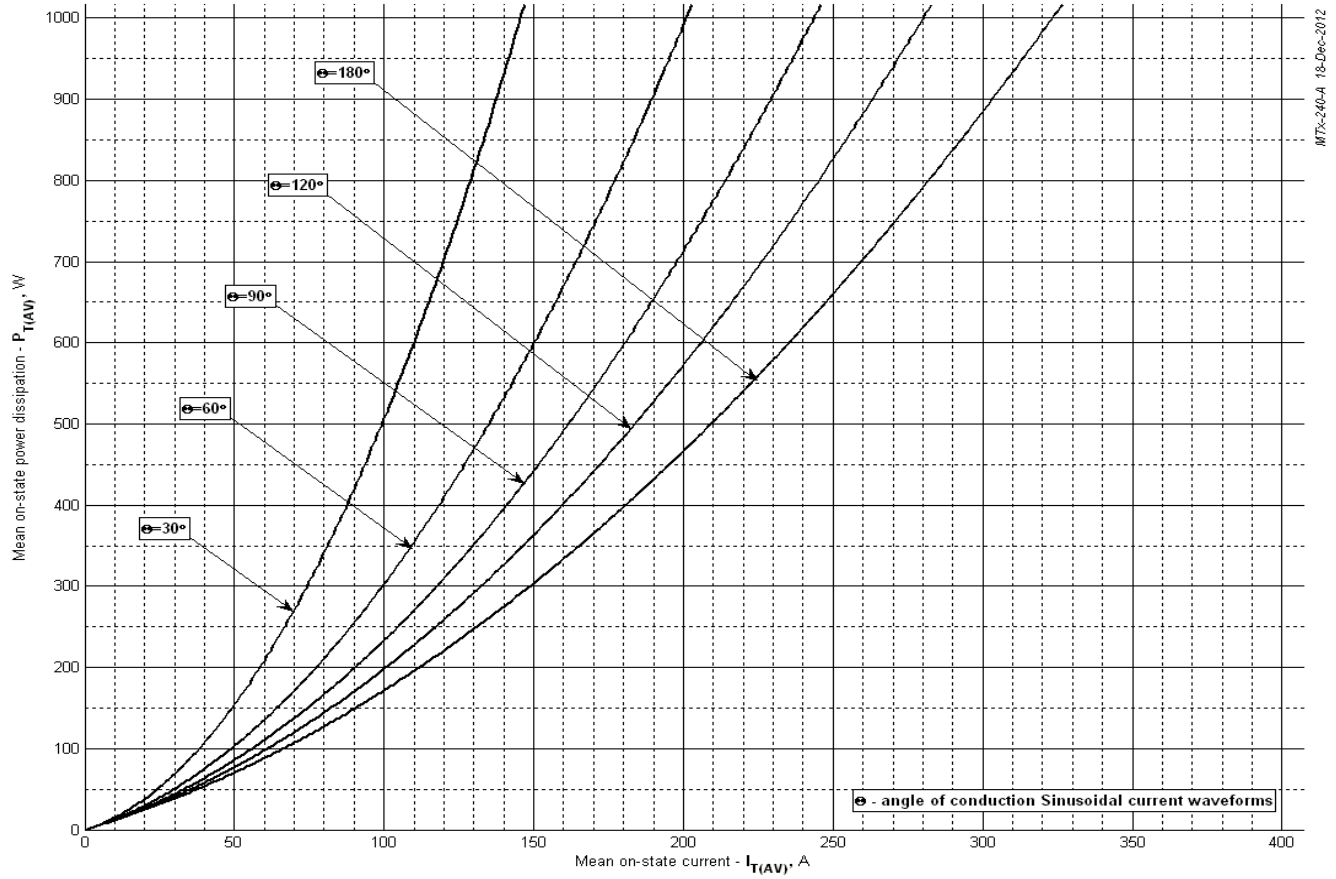


Fig 9 – On-state power loss (sinusoidal current waveforms)

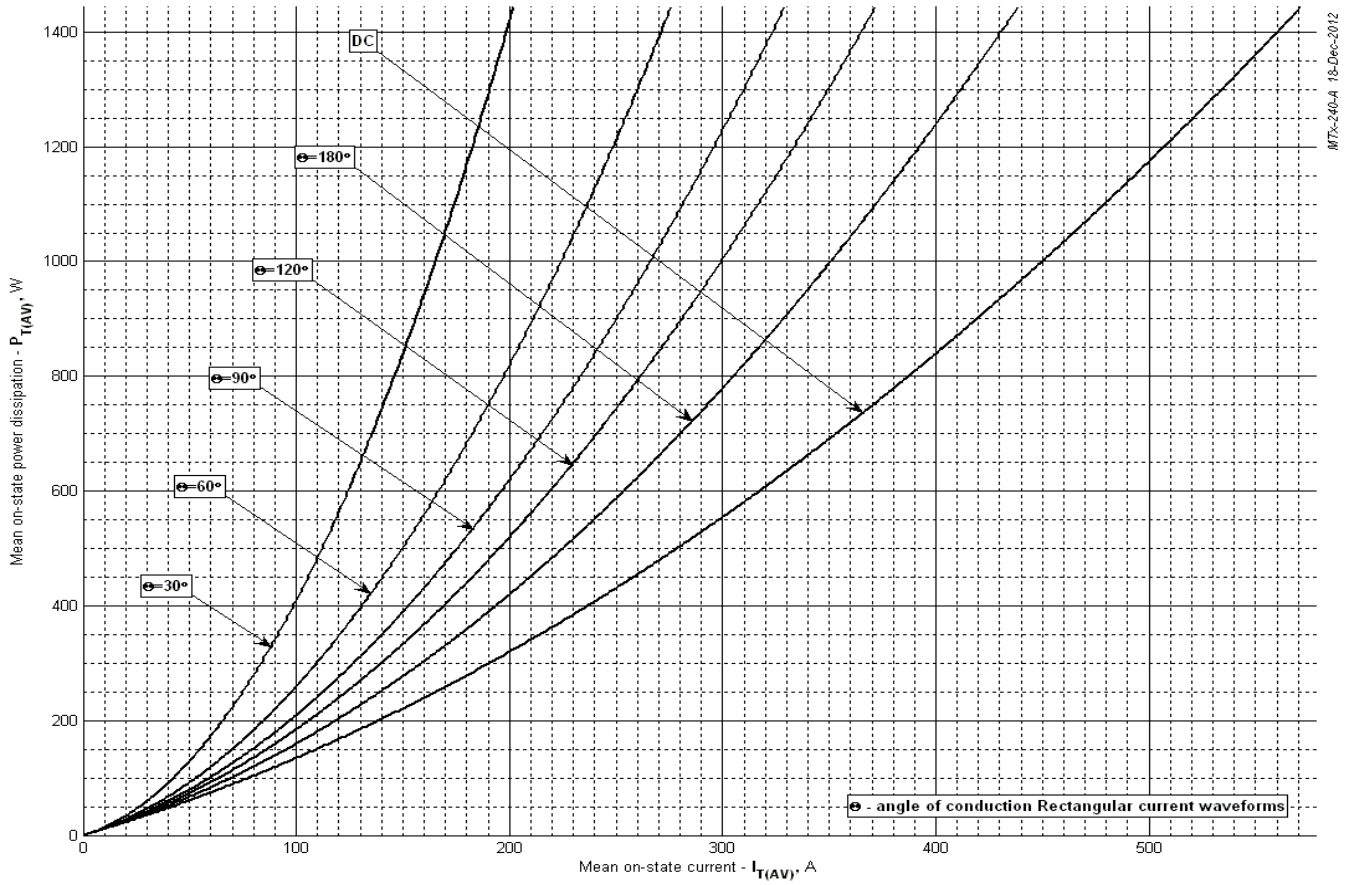


Fig 10 - On-state power loss (rectangular current waveforms)

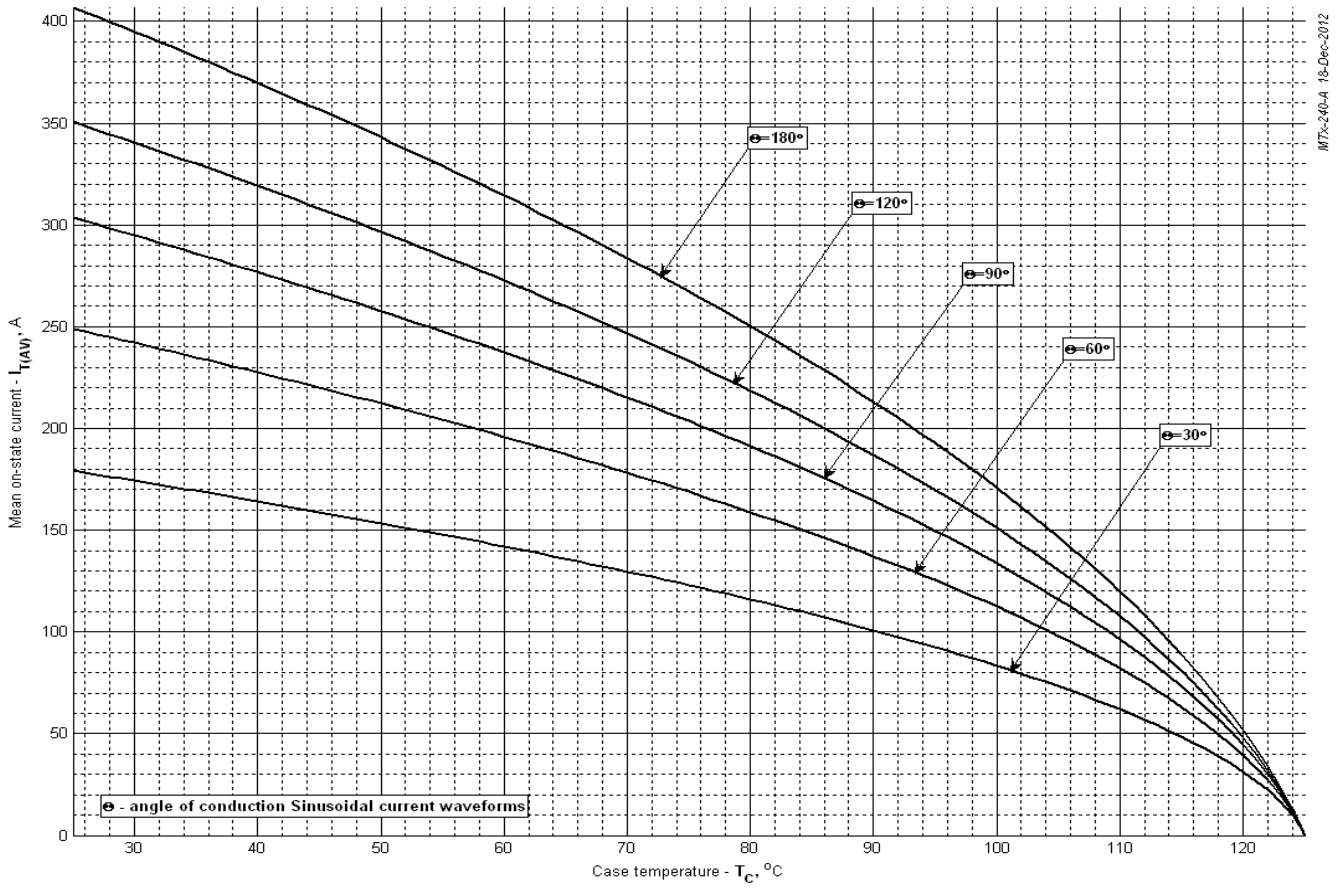


Fig 11 – Maximum case temperature (sinusoidal current waveforms)

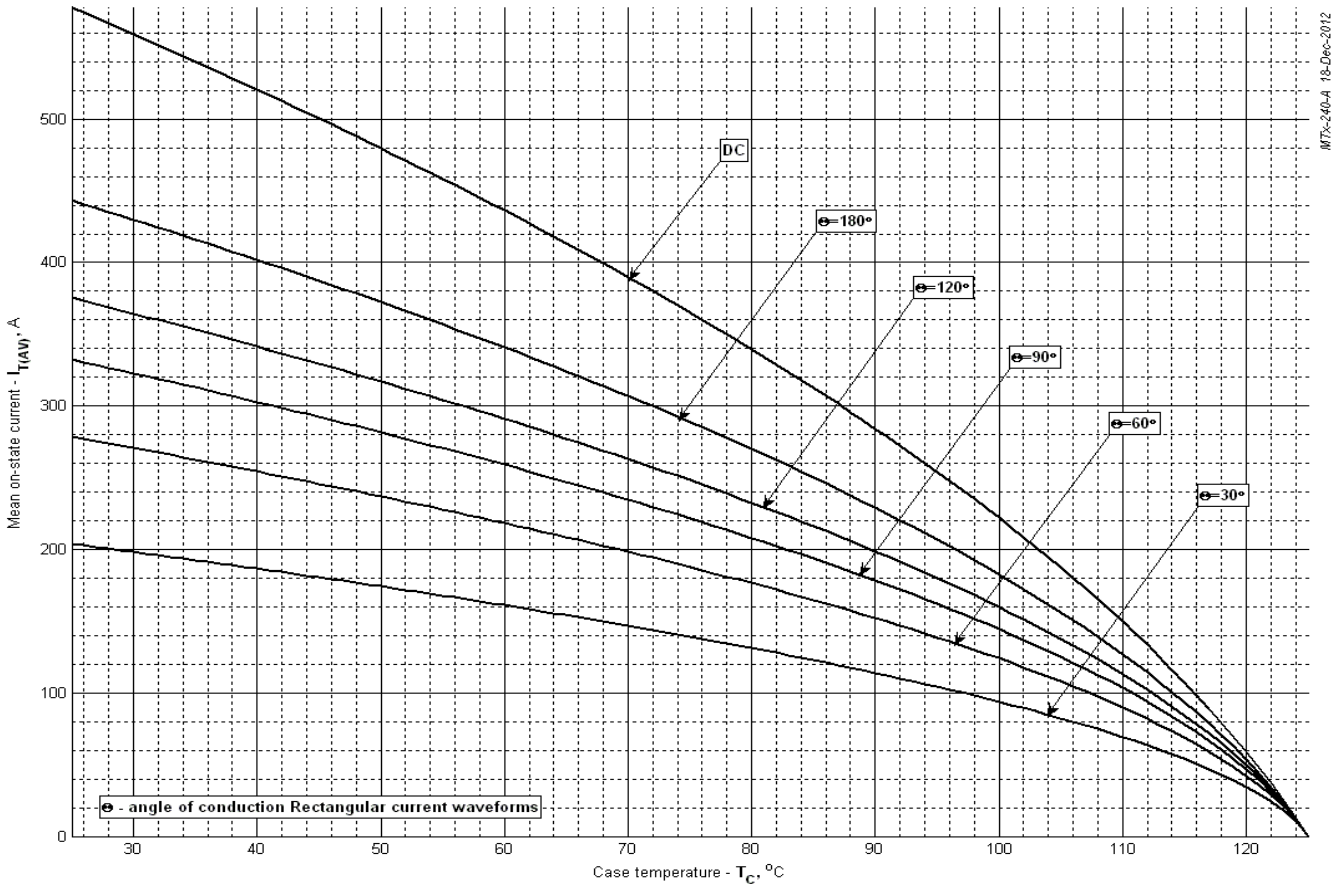


Fig 12 - Maximum case temperature (rectangular current waveforms)

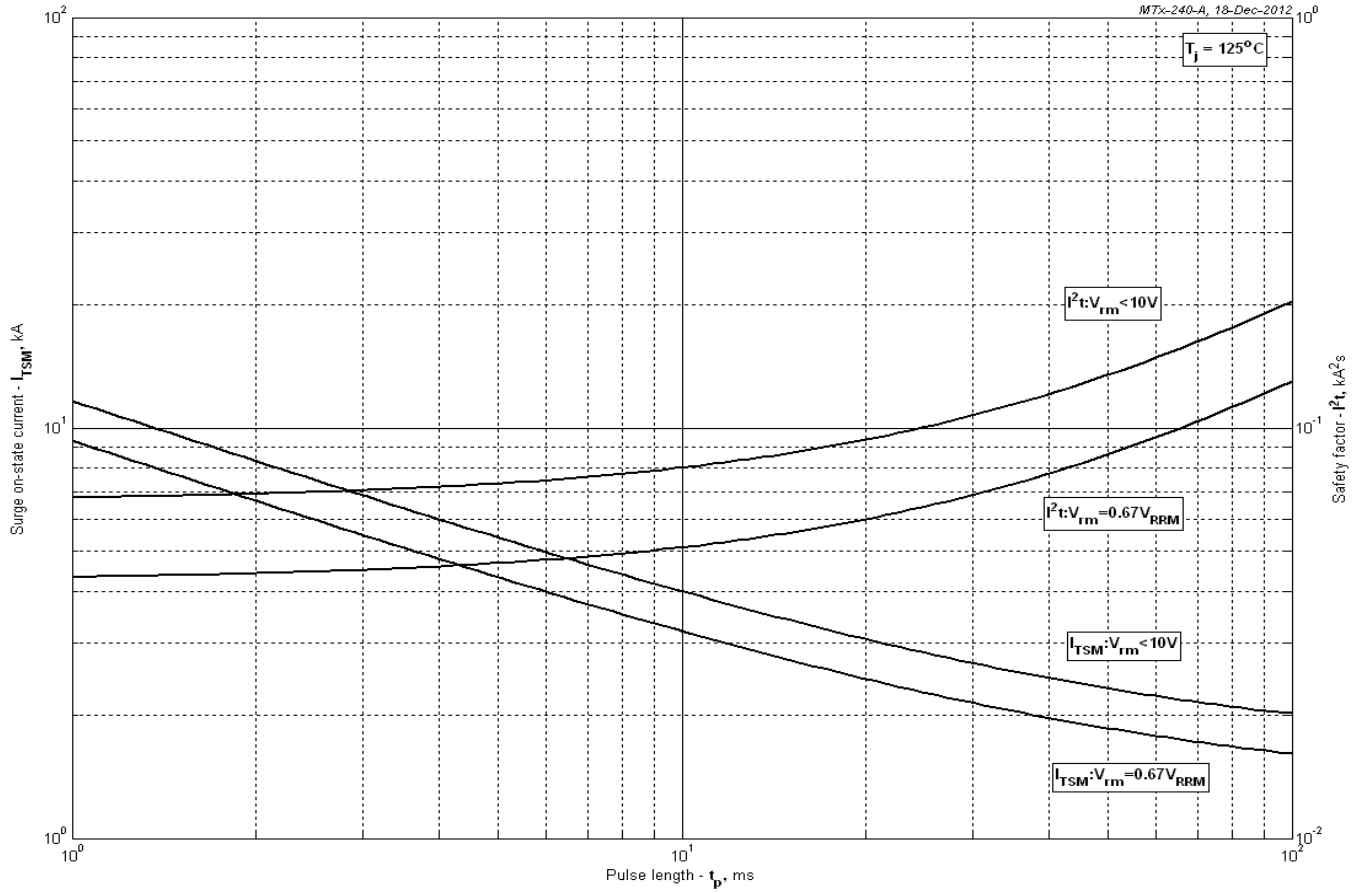


Fig 13 – Maximum surge and I^2t ratings

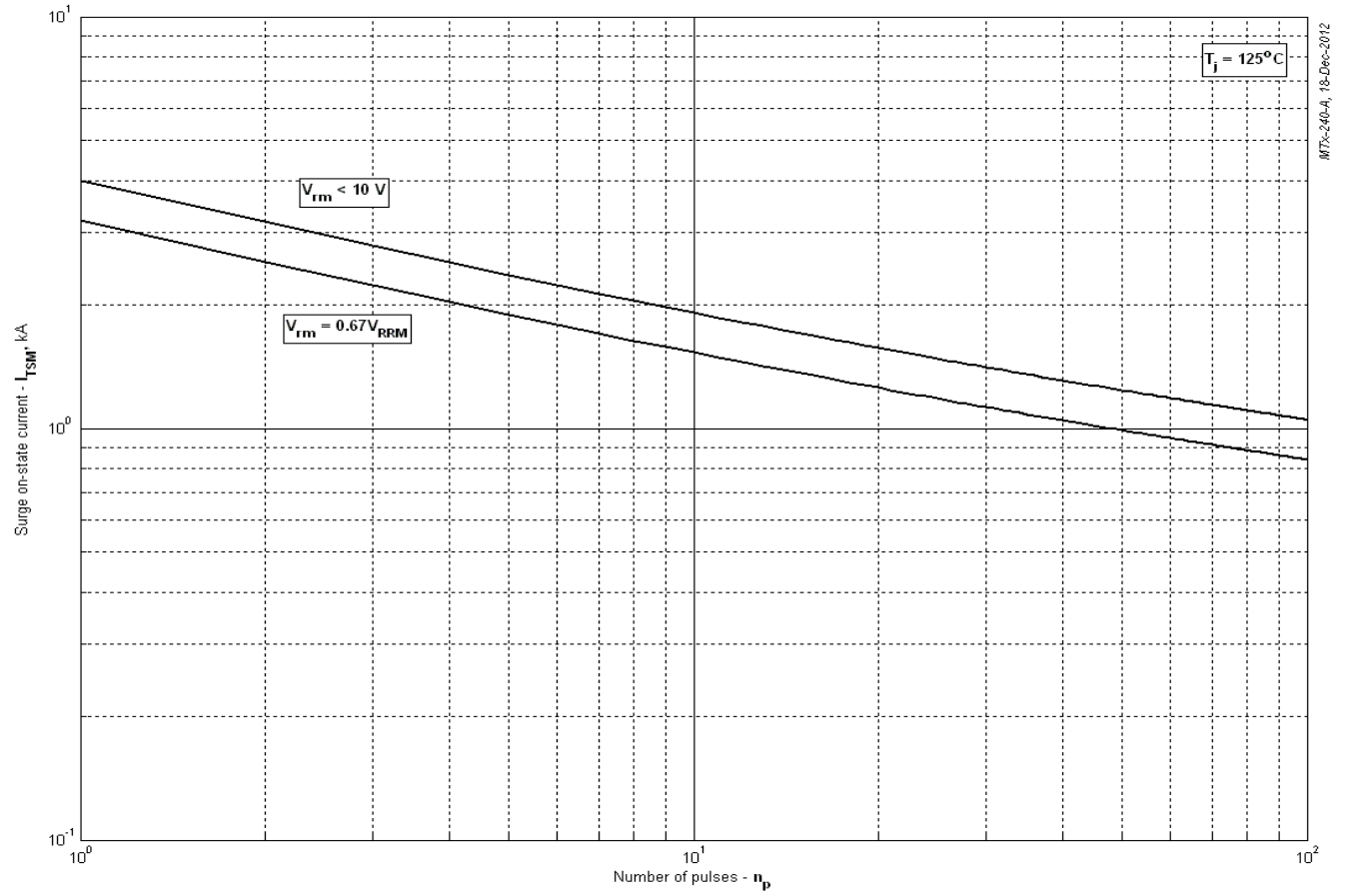


Fig 14 - Maximum surge ratings